



U.S. App. No.: 09/853,925
Filed: May 9, 2001
Group: 2813
Applicant: Chu et al
Docket No.: NSWC-1008US

Examiner Initial	Item No.	Document No.	Date	Name	Class	Subclass
Er	1US	3,642,526	Feb-72	Itoh, et al.		
	2US	3,784,402	Jan-74	Reedy, Jr.		
	3US	4,368,098	Jan-83	Manasevit		
	4US	4,765,845	Aug-88	Takada, et al.		
	5US	4,983,535	Jan-91	Blanchard		
	6US	4,996,584	Feb-91	Young, et al.		
	7US	5,036,017	Jul-91	Noda		
	8US	5,084,417	Jan-92	Joshi, et al.		
	9US	5,135,808	Aug-92	Kimock, et al.		
	10US	5,221,853	Jun-93	Joshi, et al.		
	11US	5,225,561	Jul-93	Kirlin et al.		
	12US	5,232,872	Aug-93	Ohba		
	13US	5,280,012	Jan-94	Kirlin et al.		
	14US	5,352,917	Oct-94	Ohmi		
	15US	5,400,739	Mar-95	Kao et al.		
	16US	5,453,494	Sep-95	Kirlin et al.		
	17US	5,625,204	Apr-97	Kao et al.		
	18US	5,920,080	Jul-99	Jones		
	19US	5,932,006	Aug-99	Santiago et al.		
	20US	5,955,785	Sep-99	Gardner et al.		
	21US	5,965,810	Oct-99	Holbrook		
	22US	5,968,847	Oct-99	Ye et al.		
	23US	6,077,775	Jun-00	Stumborg et al.		
	24US	6,120,844	Sep-00	Chen et al.		
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FORM PTO-1449 Modified
Documents Cited by Applicant

Page 1 (Foreign)

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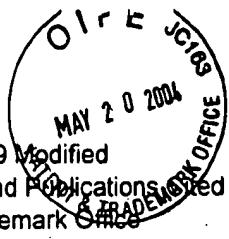
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Examiner Initial	Item No.	Foreign Patent Document No.	Date	Country	Translation (Yes/No)
Ek	1F	WO-00/11731	3/1/2000	PCT	
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List of Patents and Publications Filed by Applicant
U.S. Patent Trademark Office

Page 1 (Other Documents)

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Examiner Initial	Item No.	Other Documents (Including Author, Title, Date, Location and Pertinent Pages)
ER	10D	Vogt et al., "Dielectric Barriers for Cu Metallization Systems", <u>Materials for Advanced Metallization</u> , MAM '97, pp 51-52, 1998
ER	20D	"Electrically reprogrammable FAMOS structure," IBM Technical Disclosure Bulletin, 3/1/73, Vol. 15, Issue 10, pp. 3264-3266
ER	30D	Murarka - "Multilevel interconnections for ULSI and GSI era," Materials Science and Engineering, R19 (1997), pp. 87-151
ER	40D	Murarka - "Diffusion Barriers - for Thin Film Metallizations," Defect and Diffusion Forum, Vol. 59 (1998), pp. 99-110
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